



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

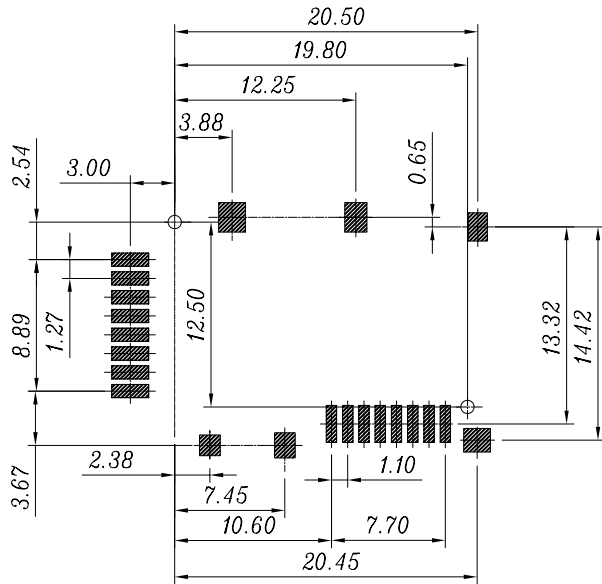
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

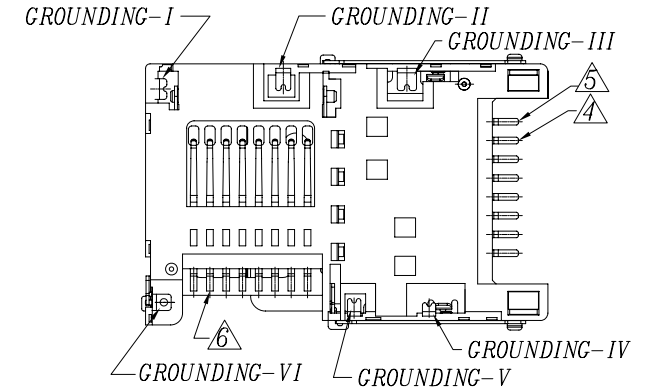
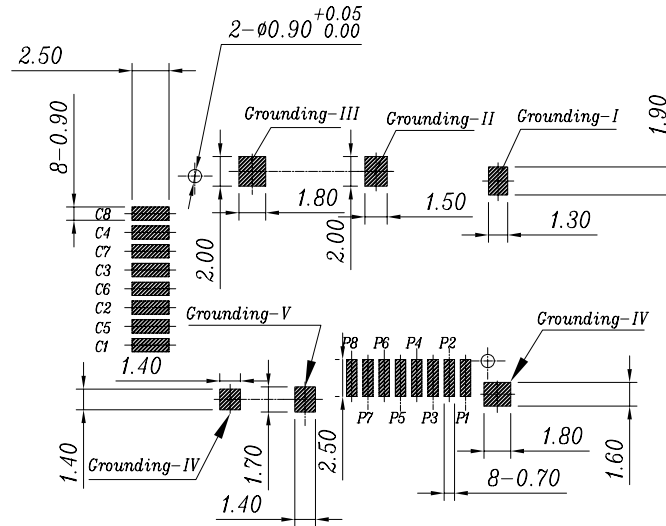




REV.	ECN.NO.	MODIFY.CONTENT	DATE
E	ES.D0906.017	add post length	2009/06/04
F	ECM0030264	塑胶底部减胶	03/08'10
G	ECNH090675	胶芯增加掏料	9/27'11



RECOMMENDER P.C.B LAYOUT  
(ALL TOLERANCES:0.03mm)



**NOTE:**

- MATERIAL**  
A.INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,UL94 V-0.  
B.SHELL: STAINLESS STEEL.  
C.CONTACT: COPPER ALLOY.
- PLATED:**  
CONTACT AREA: GOLD 1~50u" SELECTIVE  
SOLDER TAIL: TIN PLATED OR GOLD FLASH  
UNDERPLATING :50u" NICKEL
- PAD: GOLD PLATING OVER NICKEL.**

SIM pin assignment		Micro SD pin assignment	
PIN#	Name	PIN#	Name
C1	VCC	P1	DAT2
C2	RST	P2	CD/DAT3 <sup>2</sup>
C3	CLK	P3	CMD
C4	Reserved	P4	VDD
C5	GND	P5	CLK
C6	VPP	P6	SS
C7	I/O	P7	DAT0
C8	Reserved	P8	DAT1

PART. NO:  
10100492\*\*

- 17: Contact area 1u", Solder tail plating gold flash
- 18: Contact area 3u", Solder tail plating gold flash
- 19: Contact area 5u", Solder tail plating gold flash
- 20: Contact area 15u", Solder tail plating gold flash
- 21: Contact area 30u", Solder tail plating gold flash
- 22: Contact area 50u", Solder tail plating gold flash

**MATERIALS & PLATINGS TABLE**

ITEM	DESCRIPTION	Q'TY	MATERIAL
△	TERMINAL/GROUNDING	8	PHOSPHOR BRONZE(t=0.20)
△	SIM TERMINAL-II	4	PHOSPHOR BRONZE(t=0.20)
△	SIM TERMINAL-I	4	PHOSPHOR BRONZE(t=0.20)
△	MICRO SD SHELL	1	STAINLESS STEEL.(t=0.20)
△	SIM SHELL	1	STAINLESS STEEL.(t=0.20)
△	INSULATOR	1	LCP UL 94V-0
	ITEM DESCRIPTION	Q'TY	MATERIAL

GENERAL TOLERANCE	TOLERANCE	FILE.NO.	10100492	PART.NO.	10100492**	DRAWN	Yan.he
X±0.50	x.°±5°	REV.	G	TITLE	SIM+MICRO SD CONN.	CHECKED	
.X±0.38	.x°±2°	SIZE		SHEET	2/2	APPROVED	
.XX±0.25	.xx°±1°	A4					

MATERIAL	SCALE	2:1	
DATE	9/27'2011	UNIT	mm
Amphenol Shouhmin Industry			